
Multilayer Ceramic Capacitor

- High Frequency -



Multilayer Ceramic Capacitor - High Frequency

■ INTRODUCTION

MLCC for high frequency application is made of many layers of Class I(C0G, etc) ceramic and Cu inner electrodes like sandwich. Class I(C0G, etc) ceramic has a small TCC(Temperature Coefficient of Capacitance), a better frequency performance and a low ESR(Equivalent Series Resistance) value. Therefore, it is used in RF applications such as cellular phone, tuner, and so on.

■ FEATURE AND APPLICATION

● Feature

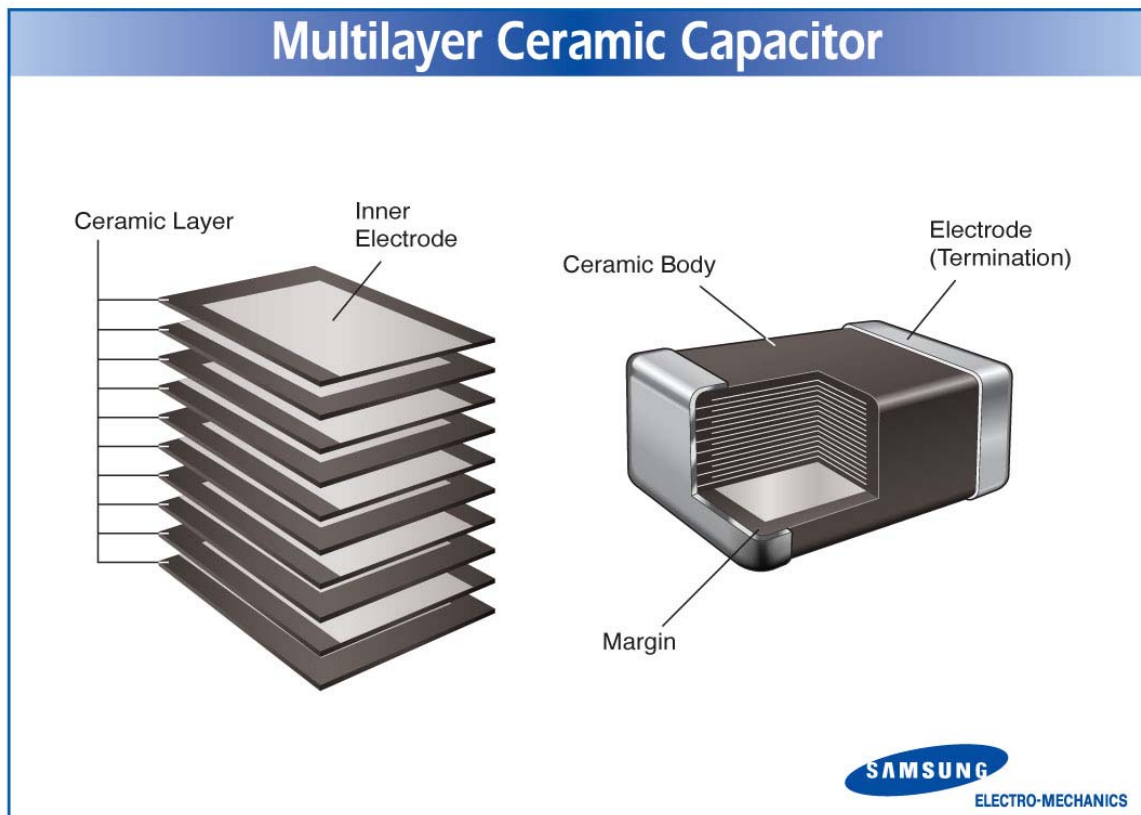
- Miniature Size
- Wide Capacitance and Voltage Range
- Highly Reliable Performance
- Tape & Reel for Surface Mount Assembly
- Low ESR
- High Q at High Frequencies
- Stable Temperature Dependence of Capacitance

● Application

- High frequency module and high power circuit

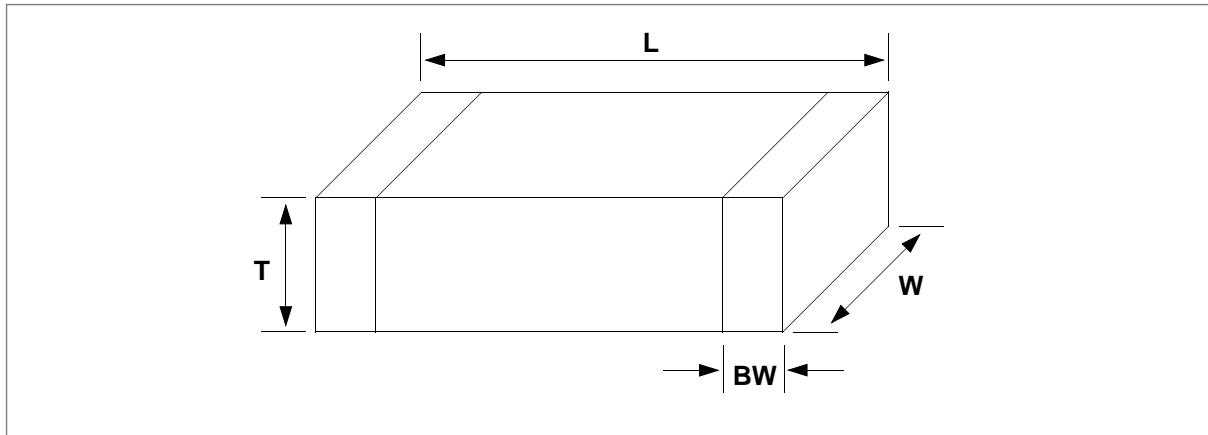
Multilayer Ceramic Capacitor - High Frequency

■ STRUCTURE



Multilayer Ceramic Capacitor - High Frequency

■ APPEARANCE AND DIMENSION



CODE	EIA CODE	DIMENSION (mm)			
		L	W	T (MAX)	BW
03	0201	0.6 ± 0.03	0.3 ± 0.03	0.3 ± 0.03	0.15 ± 0.05
05	0402	1.0 ± 0.05	0.5 ± 0.05	0.5 ± 0.05	$0.2+0.15/-0.1$

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PREVIOUS PART NUMBERING

<u>CL</u>	<u>10</u>	<u>C</u>	<u>101</u>	<u>J</u>	<u>B</u>	<u>G</u>	<u>C</u>
①	②	③	④	⑤	⑥	⑦	⑧

- ① SAMSUNG Multilayer Ceramic Capacitor
- ② Type(Size)
- ③ Capacitance Temperature Characteristics("C" only)
- ④ Nominal Capacitance
- ⑤ Capacitance Tolerance
- ⑥ Rated Voltage
- ⑦ Code "G" : Cu-Inner electrode
- ⑧ Packaging Type

③ TEMPERATURE CHARACTERISTICS

▶ CLASS I (Temperature Compensating type)

Symbol	EIA Code	Temperature Coefficient(PPM/°C)	※ Temperature Characteristics	Operation Temperature Range
C	C0G(CH)	0 ± 30	CΔ	-55 ~ +125°C

※ Temperature Characteristics

Temperature Characteristics	below 2.0pF	2.2 ~ 3.9pF	above 4.0pF	above 10pF
CΔ	C0G	C0G	C0G	C0G
PΔ	-	P2J	P2H	P2H
RΔ	-	R2J	R2H	R2H
SΔ	-	S2J	S2H	S2H
TΔ	-	T2J	T2H	T2H
UΔ	-	U2J	U2J	U2J

K : ±250 PPM/°C
 J : ±120 PPM/°C
 H : ±60 PPM/°C
 G : ±30 PPM/°C

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④ NOMINAL CAPACITANCE

The nominal capacitance value is expressed in pico-farad(pF) and identified by three-digits. The first two digits represent significant figures and the last digit specifies the number of zeros to follow. For values below 1pF, the letter "R" is used as the decimal point.

example)

100	:	10×10^0	=	10pF
102	:	10×10^2	=	1000pF
020	:	2×10^0	=	2pF
1R5	:	1.5pF		

⑤ CAPACITANCE TOLERANCE

Temperature Characteristics	Symbol	Capacitance tolerance	Capacitance range	capacitance step
C0G(NPO) or T.C Series	B	$\pm 0.1\text{pF}$	0.5~2.0pF	0.1pF
			2.0~5.0pF	E-24 step
	C	$\pm 0.25\text{pF}$	<10pF	E-24 step
	D	$\pm 0.50\text{pF}$		
	F	$\pm 1\%$	$\geq 10\text{pF}$	E-24 step
J	$\pm 5\%$	E-12 step		

※ Please consult us for special tolerances.

⑥ RATED VOLTAGE

Symbol	Rated Voltage(Vdc)
A	25V
B	50V

⑦ Type of Inner electrode

Symbol	Description of the Code
G	Copper inner electrode-standard thickness

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⑧ PACKAGING TYPE

Symbol	Packaging	Symbol	Packaging
B	Bulk	F	Embossed Tape, 13" Reel
P	Cassette	L	Paper 13" Reel
C	Paper Tape, 7" Reel	O	Paper 10" Reel
D	Paper Tape, 13" Reel	S	Embossed Tape, 10" Reel
E	Embossed Tape, 7" Reel		

▶ STANDARD CAPACITANCE STEP

Series	Capacitance step											
E- 3	1.0				2.2				4.7			
E- 6	1.0		1.5		2.2		3.3		4.7		6.8	
E-12	1.0	1.2	1.5	1.8	2.2	2.7	3.3	3.9	4.7	5.6	6.8	8.2
E-24	1.0	1.2	1.5	1.8	2.2	2.7	3.3	3.9	4.7	5.6	6.8	8.2
	1.1	1.3	1.6	2.0	2.4	3.0	3.6	4.3	5.1	6.2	7.5	9.1

※ Standard Capacitance is " Each step $\times 10^n$ "

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■ NEW PART NUMBERING

CL	10	C	101	J	B	8	G	N	N	C
①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩	⑪

- ① SAMSUNG Multilayer Ceramic Capacitor
- ② Size(mm)
- ③ Capacitance Temperature Characteristic
- ④ Nominal Capacitance
- ⑤ Capacitance Tolerance
- ⑥ Rated Voltage
- ⑦ Thickness Option
- ⑧ Product & Plating Method
- ⑨ Samsung Control Code
- ⑩ Reserved For Future Use
- ⑪ Packaging Type

① PRODUCT ABBREVIATION

Symbol	Product Abbreviation
CL	SAMSUNG Multilayer Ceramic Chip Capacitor

② SIZE(mm)

Symbol	Size(mm)	
	Length	Width
03	0.6	0.3
05	1.0	0.5

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③ TEMPERATURE CHARACTERISTICS

▶ CLASS I (Temperature Compensating type)

Symbol	EIA Code	Temperature Coefficient(PPM/°C)	※ Temperature Characteristics	Operation Temperature Range
C	C0G(CH)	0 ± 30	CΔ	-55 ~ +125°C

※ Temperature Characteristics

Temperature Characteristics	below 2.0pF	2.2 ~ 3.9pF	above 4.0pF	above 10pF
CΔ	C0G	C0G	C0G	C0G
PΔ	-	P2J	P2H	P2H
RΔ	-	R2J	R2H	R2H
SΔ	-	S2J	S2H	S2H
TΔ	-	T2J	T2H	T2H
UΔ	-	U2J	U2J	U2J

☞ K : ±250 PPM/°C
 J : ±120 PPM/°C
 H : ±60 PPM/°C
 G : ±30 PPM/°C

④ NOMINAL CAPACITANCE

Nominal capacitance is identified by 3 digits.

The first and second digits identify the first and second significant figures of the capacitance.

The third digit identifies the multiplier. 'R' identifies a decimal point.

● Example

Symbol	Nominal Capacitance
1R5	1.5pF
103	10,000pF, 10nF, 0.01 μF
104	100,000pF, 100nF, 0.1 μF

⑤ CAPACITANCE TOLERANCE

Symbol	Tolerance	Nominal Capacitance
B	±0.1pF	Less than 10pF (Including 10pF)
C	±0.25pF	
D	±0.5pF	
F	±1%	More than 10pF
J	±5%	

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⑥ RATED VOLTAGE

Symbol	Rated Voltage	Symbol	Rated Voltage
A	25V	B	50V

⑦ THICKNESS OPTION

Type	Symbol	Thickness(T)	Spec
0603	3	0.30	±0.03
1005	5	0.50	±0.05

⑧ PRODUCT & PLATING METHOD

Symbol	Electrode	Termination	Plating Type
A	Pd	Ag	Sn_100%
N	Ni	Cu	Sn_100%
G	Cu	Cu	Sn_100%

⑨ SAMSUNG CONTROL CODE

Symbol	Description of the code	Symbol	Description of the code
A	Array (2-element)	N	Normal
B	Array (4-element)	P	Automotive
C	High - Q	W	3 Terminal EMI Filter
L	LICC		

⑩ RESERVED FOR FUTURE USE

Symbol	Description of the code
N	Reserved for future use

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① PACKAGING TYPE

Symbol	Packaging Type	Symbol	Packaging Type
B	Bulk	F	Embossing 13" (10,000EA)
P	Bulk Case	L	Paper 13" (15,000EA)
C	Paper 7"	O	Paper 10"
D	Paper 13" (10,000EA)	S	Embossing 10"
E	Embossing 7"		

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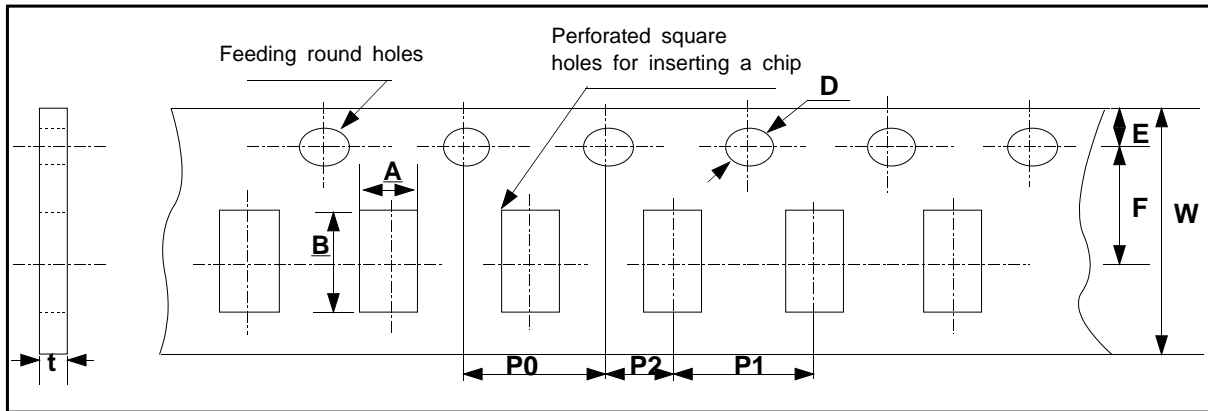
▶ CAPACITANCE vs CHIP THICKNESS STANDARD

Description		0603 type (0201)	1005 type (0402)
Dimension(mm)	L	0.6±0.03	1.0±0.05
	W	0.3±0.03	0.5±0.05
	T	0.3±0.03	0.5±0.05
MAX CAPACITANCE(pF)	C	25V	-
		50V	10

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PACKAGING

CARDBOARD PAPER TAPE

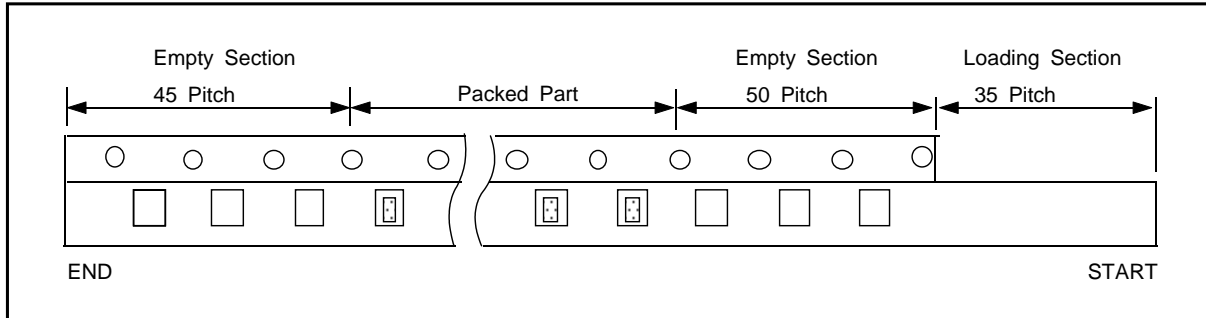


unit : mm

Symbol		W	F	E	P1	P2	P0	D	t	A	B
Type											
D i m e n s i o n	03	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	2.0 ±0.05	2.0 ±0.05	4.0 ±0.1	Φ1.5 +0.1/-0	0.37 ±0.03	0.38 ±0.03	0.68 ±0.03
	05										

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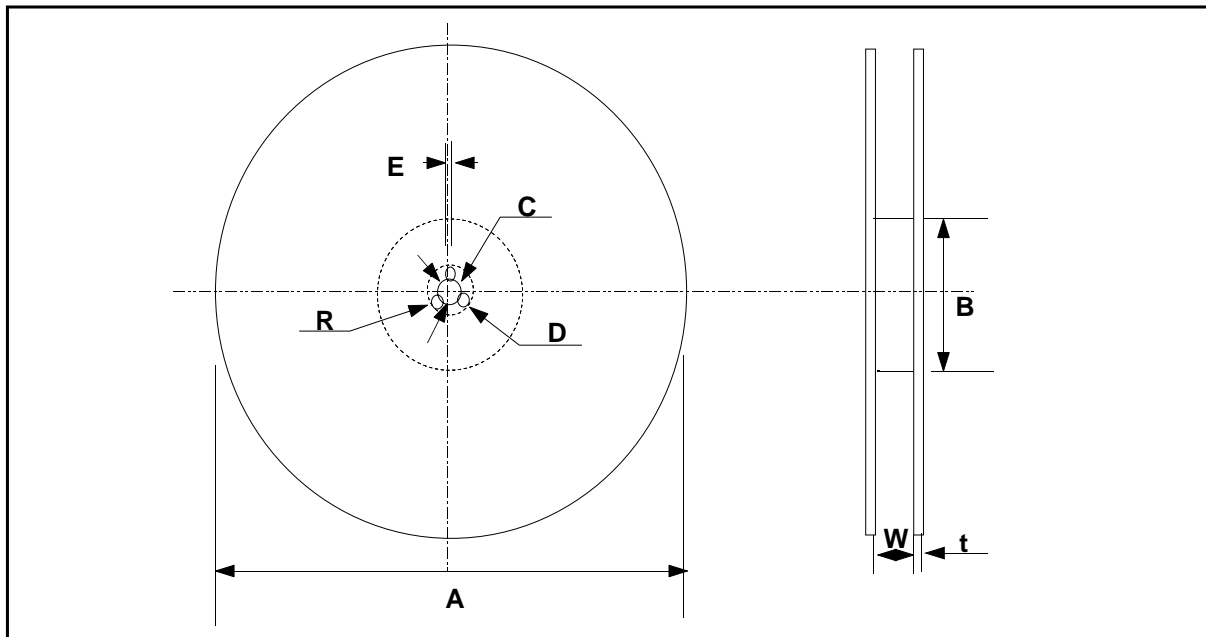
● TAPING SIZE



unit : pcs

Symbol	Cardboard Paper Tape
7" Reel	10000
13" Reel	10000

● REEL DIMENSION



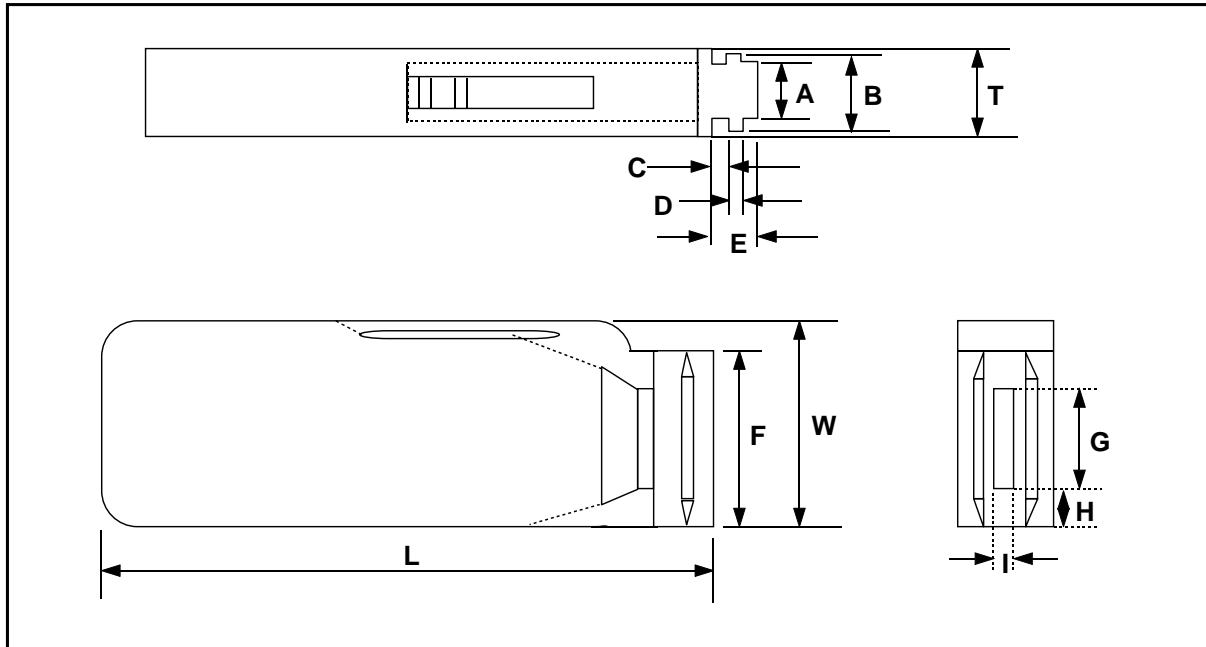
unit : mm

Symbol	A	B	C	D	E	W	t	R
7" Reel	$\phi 178 \pm 2.0$	min. $\phi 50$	$\phi 13 \pm 0.5$	21 ± 0.8	2.0 ± 0.5	10 ± 1.5	0.8 ± 0.2	1.0
13" Reel	$\phi 330 \pm 2.0$	min. $\phi 70$						

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● BULK CASE PACKAGING

- Bulk case packaging can reduce the stock space and transportation costs.
- The bulk feeding system can increase the productivity.
- It can eliminate the components loss.



Symbol	A	B	T	C	D	E
Dimension	6.8 ± 0.1	8.8 ± 0.1	12 ± 0.1	$1.5 + 0.1 / - 0$	$2 + 0 / - 0.1$	4.7 ± 0.1

Symbol	F	W	G	H	L	I
Dimension	$31.5 + 0.2 / - 0$	$36 + 0 / - 0.2$	19 ± 0.35	7 ± 0.35	110 ± 0.7	5 ± 0.35

● QUANTITY

Size	03(0201)	05(0402)
Quantity	N/A	50,000

* N/A : Not adapted

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■ CHARACTERISTIC MAP

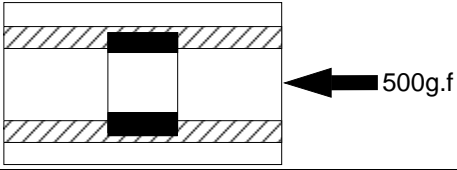
● CAPACITANCE RANGE

▶ CLASS I

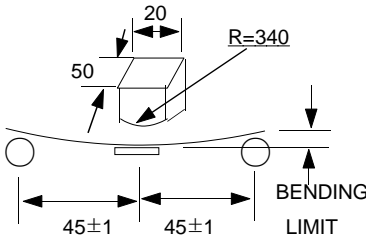
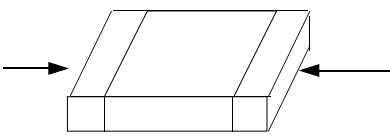
Temperature Characteristics	Size	Voltage	Capacitance Range (pF)									
			0.5	10	100	1000	10000	100000	1000000	10000000	100000000	
C(COG)	03 (0201)	25V	█ 20									
	05 (0402)	50V	█ 10									

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RELIABILITY TEST DATA

NO	ITEM		PERFORMANCE	TEST CONDITION		
1	APPEARANCE		NO ABNORMAL EXTERIOR APPEARANCE.	THROUGH MICROSCOPE(×10)		
2	INSULATION RESISTANCE		10,000MΩ OR 500MΩ·μF PRODUCT WHICHEVER IS SMALLER. (RATED VOLTAGE IS BELOW 16V : 10,000MΩ OR 100MΩ·μF)	RATED VOLTAGE SHALL BE APPLIED. MEASUREMENT TIME IS 60 ~ 120sec RATED VOLTAGE TIME 60 SEC.		
3	WITHSTANDING VOLTAGE		NO DIELECTRIC BREAKDOWN OR MECHANICAL BREAKDOWN.	CLASS I : 300% OF THE RATED VOLTAGE FOR 1-5SEC,		
4	CAPACITANCE	CLASS I	WITHIN THE SPECIFIED TOLERANCE	CAPACITANCE	FREQUENCY	VOLTAGE
				1,000pF AND BELOW	1MHz±10%	0.5 ~ 5 Vrms
MORE THAN 1,000pF	1kHz±10%					
5	Q	CLASS I	OVER 30pF : Q ≥1,000 LESS THAN 30pF : Q ≥400 +20C (C : CAPACITANCE)	CAPACITANCE	FREQUENCY	VOLTAGE
				1,000pF AND BELOW	1MHz±10%	0.5 ~ 5 Vrms
				MORE THAN 1,000pF	1kHz±10%	
6	ADHESIVE STRENGTH OF TERMINATION		NO INDICATION OF PEELING OCCUR ON THE TERMINAL ELECTRODE.	A 500g.f PRESSURE SHALL BE APPLIED FOR 10±1 SECOND. 		
7	ESR		2pF < C ≤ 5pF : BELOW 200mΩ 5pF < C ≤ 10pF : BELOW 150mΩ 10pF < C ≤ 33pF : BELOW 100mΩ	TEST EQUIPMENT : E4991B CONDITION: FREQUENCY 1GHz, Osc 100m AT ROOM TEMPERATURE		

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NO	ITEM	PERFORMANCE	TEST CONDITION									
8	APPEARANCE	NO MECHANICAL DAMAGE SHALL OCCUR.	BENDING SHALL BE APPLIED TO THE LIMIT(1mm) WITH 0.3mm/SEC. 									
	BENDING STRENGTH	CHARACTER CHANGE OF CAPACITANCE CLASS I WITHIN $\pm 5\%$ OR $\pm 0.5\text{pF}$ WHICHEVER IS LARGER										
9	SOLDERABILITY	MORE THAN 95% OF THE TERMINAL SURFACE IS TO BE SOLDERED NEWLY, SO METAL PART(A) DOES NOT COME OUT OR DISSOLVE.  IN PB--FREE PART, MORE THAN 95% OF THE TERMINAL SURFACE IS TO BE SOLDERED NEWLY	SOLDER TEMPERATURE : $230\pm 5^\circ\text{C}$ DIP TIME : 3 ± 1 Sec SOLDER : H63A FLUX : RMA TYPE *PB-FREE SOLDER TEMPERATURE : $260\pm 5^\circ\text{C}$ SOLDER : Sn96.5-3Ag-0.5Cu Flux : RMA TYPE DIP TIME : 3 ± 0.1 Sec * PRE-HEATING : AT $80\sim 120^\circ\text{C}$ FOR 10~30SEC.									
10	APPEARANCE	NO MECHANICAL DAMAGE SHALL OCCUR.	DIP : SOLDER TEMPERATURE OF $270\pm 5^\circ\text{C}$ DIP TIME : 10 ± 1 SEC. EACH TERMINATION SHALL BE FULLY IMMERSSED AND PREHEATED AS FOLLOWING: <table border="1" data-bbox="1029 1456 1412 1612"> <thead> <tr> <th>STEP</th> <th>TEMP.($^\circ\text{C}$)</th> <th>TIME (SEC.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>80~100</td> <td>60</td> </tr> <tr> <td>2</td> <td>150~180</td> <td>60</td> </tr> </tbody> </table> MEASURE AT ROOM TEMP. AFTER COOLING FOR CLASS I : 24 ± 2 HOURS	STEP	TEMP.($^\circ\text{C}$)	TIME (SEC.)	1	80~100	60	2	150~180	60
	STEP	TEMP.($^\circ\text{C}$)		TIME (SEC.)								
	1	80~100		60								
	2	150~180		60								
	RESISTANCE TO SOLDERING HEAT	CHARACTERISTIC		CAP. CHANGE								
CAPACITANCE		CLASS I	WITHIN $\pm 2.5\%$ OR $\pm 0.25\text{pF}$ WHICHEVER IS LARGER									
Q	CLASS I	30pF AND OVER : $Q \geq 1000$ LESS THAN 30pF : $Q \geq 400+20 \times C$										
INSULATION RESISTANCE	TO SATISFY THE SPECIFIED INITIAL VALUE.											
WITHSTANDING VOLTAGE	TO SATISFY THE SPECIFIED INITIAL VALUE.											

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NO	ITEM	PERFORMANCE	TEST CONDITION			
11	VIBRATION TEST	APPEARANCE	NO MECHANICAL DAMAGE SHALL OCCUR.	<p>THE CAPACITOR SHALL BE SUBJECTED TO A HARMONIC MOTION HAVING A TOTAL AMPLITUDE OF 1.5mm.</p> <p>THE ENTIRE FREQUENCY RANGE, FROM 10 TO 55Hz AND RETURN TO 10Hz, SHALL BE TRAVERSED IN 1 MINUTE.</p> <p>THIS CYCLE SHALL BE PERFORMED 2 HOURS IN EACH THERE MUTUALLY PERPENDICULAR DIRECTION FOR TOTAL PERIOD OF 6 HOURS.</p>		
		CAPACITANCE	CHARACTERISTI		CAP. CHANGE	
			CLASS I		WITHIN $\pm 2.5\%$ OR $\pm 0.25\text{pF}$ WHICHEVER IS LARGER	
					CLASS II	B
			F		WITHIN $\pm 20\%$	
Q CLASS I	30pF AND OVER : $Q \geq 1000$ LESS THAN 30pF : $Q \geq 400+20 \times C$					
INSULATION RESISTANCE	TO SATISFY THE SPECIFIED INITIAL VALUE.					
12	HUMIDITY (STEADY STATE)	APPEARANCE	NO MECHANICAL DAMAGE SHALL OCCUR.	<p>TEMPERATURE : $40 \pm 2 \text{ }^\circ\text{C}$</p> <p>RELATIVE HUMIDITY : 90~95 %RH</p> <p>TEST TIME : 500 +12/-0 Hr.</p> <p>MEASURE AT ROOM TEMPERATURE AFTER COOLING FOR CLASS I : 24\pm2 Hr.</p>		
		CAPACITANCE	CHARACTERISTI C		CAPACITANCE CHANGE	
			CLASS I		WITHIN $\pm 5\%$ OR $\pm 0.5\text{pF}$ WHICHEVER IS LARGER	
		Q CLASS I	30pF AND OVER : $Q \geq 350$ 10 ~30pF : $Q \geq 275 + 2.5 \times C$ LESS THAN 10pF : $Q \geq 200 + 10 \times C$			
INSULATION RESISTANCE	MINIMUM INSULATION RESISTANCE: 1,000 M Ω OR 50M $\Omega \cdot \mu\text{F}$ PRODUCT WHICHEVER IS SMALLER.					
13	MOISTURE RESISTANCE	APPEARANCE	NO MECHANICAL DAMAGE SHALL OCCUR.	<p>APPLIED VOLTAGE : RATED VOLTAGE</p> <p>TEMPERATURE : $40 \pm 2 \text{ }^\circ\text{C}$</p> <p>RELATIVE HUMIDITY:90~95%RH</p> <p>TEST TIME : 500 +12/-0 Hr.</p> <p>CURRENT APPLIED : 50mA MAX.</p> <p><INITIAL MEASUREMENT> CLASS II SHOULD BE MEASURED INITIAL VALUE AFTER BE HEAT-TREATED FOR 1 HR IN $150^\circ\text{C}+0/-10^\circ\text{C}$ AND BE LEFT FOR 48\pm4HR AT ROOM TEMPERATURE.</p> <p><LATTER MEASUREMENT> CLASS I SHOULD BE MEASURED AFTER LEFT FOR 24\pm2 HRS IN ROOM TEMPERATURE AND HUMIDITY. CLASS II SHOULD BE MEASURED LATTER VALUE AFTER BE HEAT-TREATED FOR 1 HR IN $150^\circ\text{C}+0/-10^\circ\text{C}$ AND BE LEFT FOR 48\pm4HR AT ROOM TEMPERATURE.</p>		
		CAPACITANCE	CHARACTERISTI C		CAPACITANCE CHANGE	
			CLASS I		WITHIN $\pm 7.5\%$ OR $\pm 0.75\text{pF}$ WHICHEVER IS LARGER	
		Q CLASS I	30pF AND OVER : $Q \geq 200$ 30pF AND BELOW : $Q \geq 100 + 10/3 \times C$			
INSULATION RESISTANCE	MINIMUM INSULATION RESISTANCE: 500 M Ω OR 25M $\Omega \cdot \mu\text{F}$ PRODUCT, WHICHEVER IS SMALLER.					

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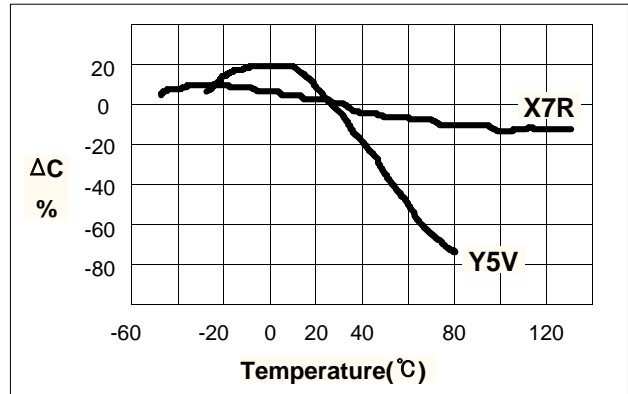
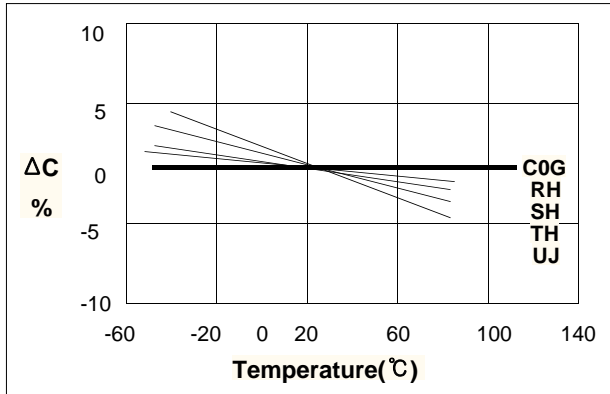
NO	ITEM	PERFORMANCE	TEST CONDITION				
14	HIGH TEMPERATURE RESISTANCE	APPEARANCE	NO MECHANICAL DAMAGE SHALL OCCUR. APPLIED VOLTAGE : 200% OF RATED VOLTAGE TEST TIME : 1000 +48/-0 Hr. CURRENT APPLIED : 50mA MAX. Temp :125 ±3℃				
		CAPACITANCE	CHARACTERISTIC	CAP. CHANGE			
			CLASS I	WITHIN ±3% OR ±0.3pF, WHICHEVER IS LARGER			
		Q CLASS I	30pF AND OVER : Q ≥ 350 10 ~ 30 pF : Q ≥ 275 + 2.5×C LESS THAN 10pF :Q ≥200 + 10×C				
		INSULATION RESISTANCE	MINIMUM INSULATION RESISTANCE: 1,000 MΩ OR 50MΩ·μF PRODUCT WHICHEVER IS SMALLER.	<INITIAL MEASUREMENT> CLASS II SHOULD BE MEASURED INITIAL VALUE AFTER BE HEAT-TREATED FOR 1 HR IN 150℃+0/-10 ℃ AND BE LEFT FOR 48±4HR AT ROOM TEMPERATURE. <LATTER MEASUREMENT> CLASS I SHOULD BE MEASURED AFTER LEFT FOR 24±2 HRS IN ROOM TEMPERATURE AND HUMIDITY. CLASS II SHOULD BE MEASURED LATTER VALUE AFTER BE HEAT-TREATED FOR 1 HR IN 150℃+0/-10 ℃ AND BE LEFT FOR 48±4HR AT ROOM TEMPERATURE.			
15	TEMPERATURE CYCLE	APPEARANCE	NO MECHANICAL DAMAGE SHALL OCCUR. CAPACITORS SHALL BE SUBJECTED TO FIVE CYCLES OF THE TEMPERATURE CYCLE AS FOLLOWING				
		CAPACITANCE	CHARACTERISTIC	CAP. CHANGE	STEP	TEMP.(℃)	TIME (MIN)
			CLASS I	WITHIN ±2.5% OR ±0.25pF WHICHEVER IS LARGER	1	MIN. RATED TEMP. +0/-3	30
		Q CLASS I	30 pF AND OVER : Q ≥ 1000 LESS THAN 30pF:Q ≥400 +20×C		2	25	2~3
		INSULATION RESISTANCE	TO SATISFY THE SPECIFIED INITIAL VALUE.	3	MAX. RATED TEMP. +3/-0	30	
4	25			2~3			
			MEASURE AT ROOM TEMPERATURE AFTER COOLING FOR CLASS I : 24±2 Hr. CLASS II : 48±4 Hr.				

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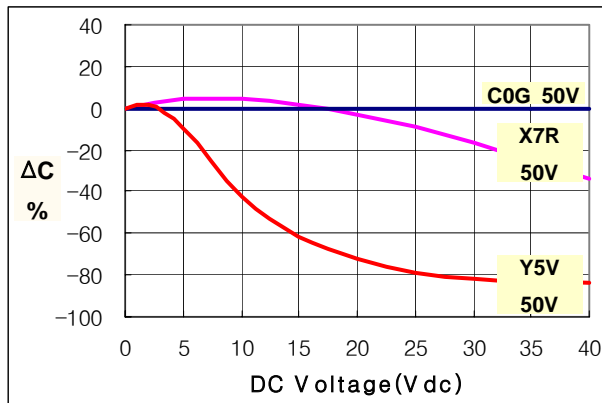
CHARACTERISTIC GRAPH

ELECTRICAL CHARACTERISTICS

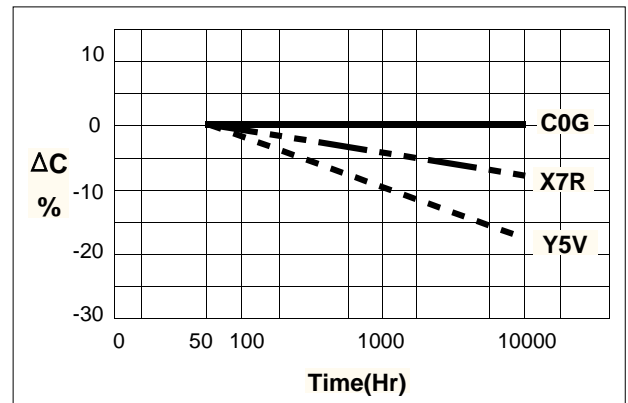
CAPACITANCE - TEMPERATURE CHARACTERISTICS



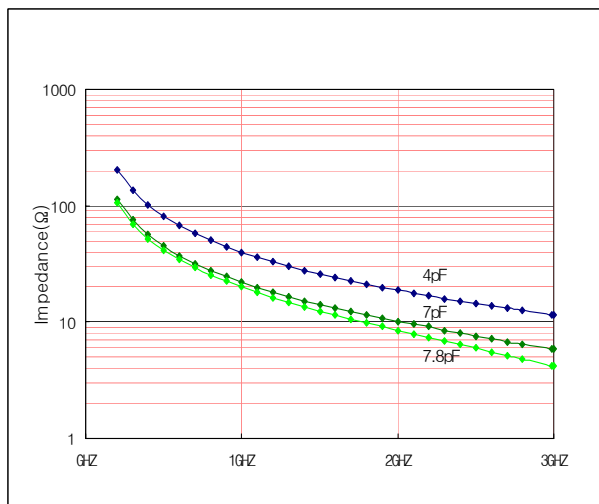
CAPACITANCE - DC VOLTAGE CHARACTERISTICS



CAPACITANCE CHANGE - AGING



IMPEDANCE - FREQUENCY CHARACTERISTICS



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■ APPLICATION MANUAL

● Storage Condition

▶ Storage Environment

The electrical characteristics of MLCCs were degraded by the environment of high temperature or humidity. Therefore, the MLCCs shall be stored in the ambient temperature and the relative humidity of less than 40°C and 70%, respectively. Guaranteed storage period is within 6 months from the outgoing date of delivery.

▶ Corrosive Gases

Since the solderability of the end termination in MLCC was degraded by a chemical atmosphere such as chlorine, acid or sulfide gases, MLCCs must be avoided from these gases.

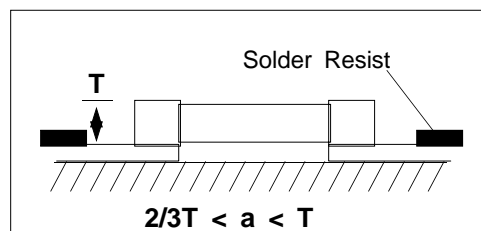
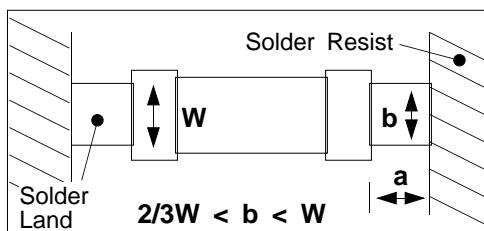
▶ Temperature Fluctuations

Since dew condensation may occur by the differences in temperature when the MLCCs are taken out of storage, it is important to maintain the temperature-controlled environment.

● Design of Land Pattern

When designing printed circuit boards, the shape and size of the lands must allow for the proper amount of solder on the capacitor. The amount of solder at the end terminations has a direct effect on the crack. The crack in MLCC will be easily occurred by the tensile stress which was due to too much amount of solder. In contrast, if too little solder is applied, the termination strength will be insufficiently. Use the following illustrations as guidelines for proper land design.

Recommendation of Land Shape and Size



● Adhesives

When flow soldering the MLCCs, apply the adhesive in accordance with the following conditions.

▶ Requirements for Adhesives

They must have enough adhesion, so that, the chips will not fall off or move during the handling of the circuit board.

They must maintain their adhesive strength when exposed to soldering temperature.

They should not spread or run when applied to the circuit board.

They should harden quickly.

They should not corrode the circuit board or chip material.

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They should be a good insulator.

They should be non-toxic, and not produce harmful gases, nor be harmful when touched.

▶ Application Method

It is important to use the proper amount of adhesive. Too little and much adhesive will cause poor adhesion and overflow into the land, respectively.

▶ Adhesive hardening Characteristics

To prevent oxidation of the terminations, the adhesive must harden at 160°C or less, within 2 minutes or less.

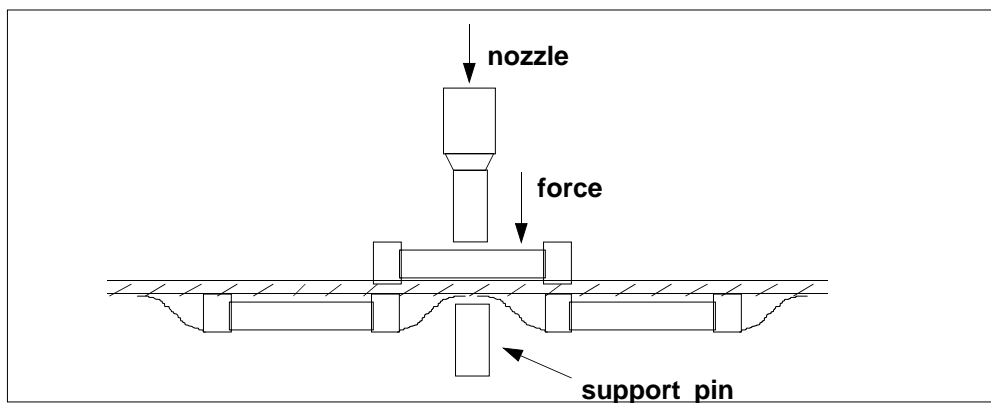
● Mounting

▶ Mounting Head Pressure

Excessive pressure will cause crack to MLCCs. The pressure of nozzle will be 300g maximum during mounting.

▶ Bending Stress

When double-sided circuit boards are used, MLCCs first are mounted and soldered onto one side of the board. When the MLCCs are mounted onto the other side, it is important to support the board as shown in the illustration. If the circuit board is not supported, the crack occur to the ready-installed MLCCs by the bending stress.



● Flux

Although the solderability increased by the highly-activated flux, increase of activity in flux may also degrade the insulation of the chip capacitors. To avoid such degradation, it is recommended that a mildly activated rosin flux (less than 0.2% chlorine) be used.

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● Soldering

Since a multilayer ceramic chip capacitor comes into direct contact with melted solder during soldering, it is exposed to potentially mechanical stress caused by the sudden temperature change. The capacitor may also be subject to silver migration, and to contamination by the flux. Because of these factors, soldering technique is critical.

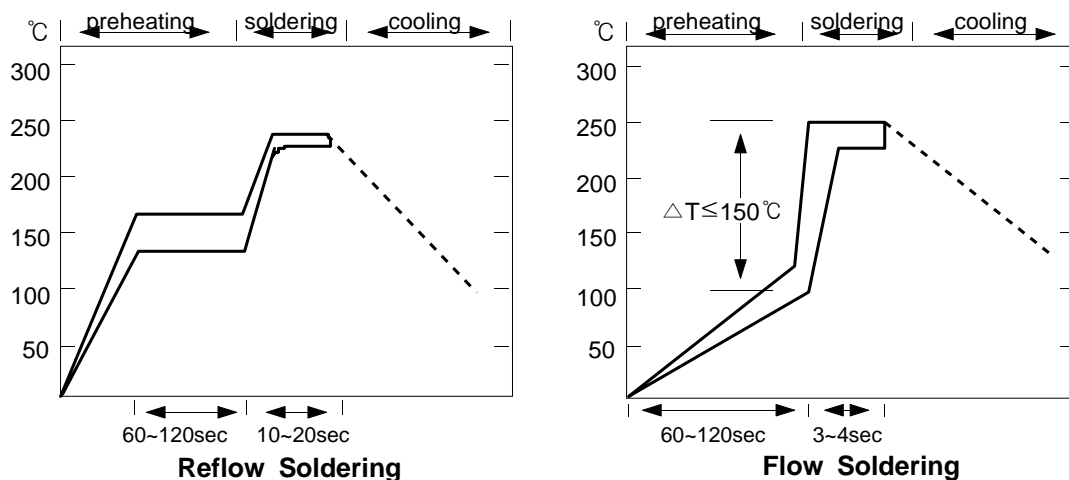
▶ Soldering Methods

Method	Classification	
Reflow soldering	- Overall heating	- Infrared rays - Hot plate - VPS(vapor phase)
	- Local heating	- Air heater - Laser - Light beam
Flow soldering	- Single wave - Double wave	-

* We recommend the reflow soldering method.

▶ Soldering Profile

To avoid crack problem by sudden temperature change, follow the temperature profile in the adjacent graph.

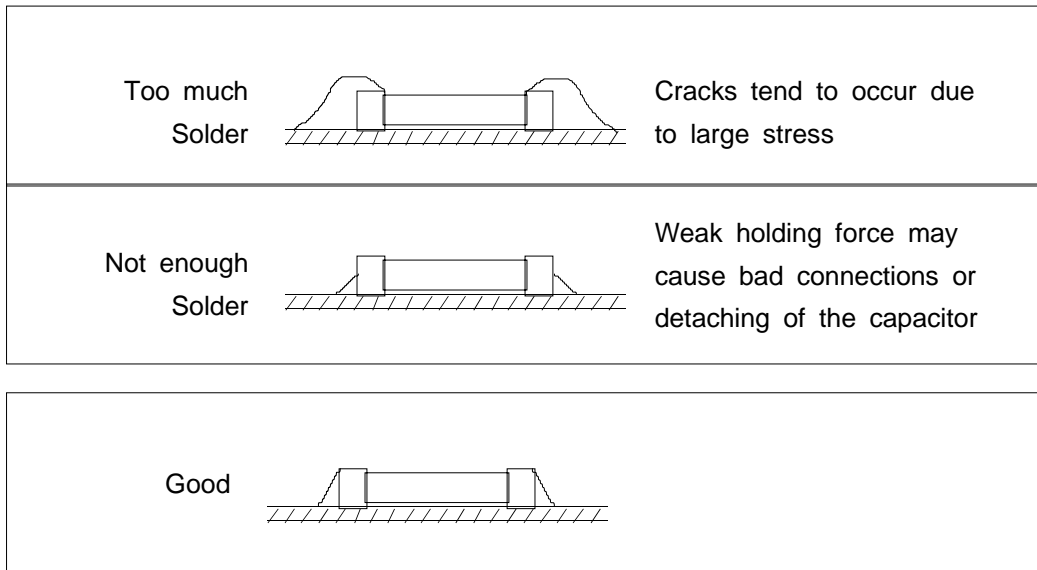


▶ Manual Soldering

Manual soldering can pose a great risk of creating thermal cracks in chip capacitors. The hot soldering iron tip comes into direct contact with the end terminations, and operator's carelessness may cause the tip of the soldering iron to come into direct contact with the ceramic body of the capacitor. Therefore the soldering iron must be handled carefully, and close attention must be paid to the selection of the soldering iron tip and to temperature control of the tip.

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► Amount of Solder



► Cooling

Natural cooling using air is recommended. If the chips are dipped into solvent for cleaning, the temperature difference(ΔT) must be less than 100°C

6-6. Cleaning

If rosin flux is used, cleaning usually is unnecessary. When strongly activated flux is used, chlorine in the flux may dissolve into some types of cleaning fluids, thereby affecting the chip capacitors. This means that the cleaning fluid must be carefully selected, and should always be new.

► Notes for Separating Multiple, Shared PC Boards.

A multi-PC board is separated into many individual circuit boards after soldering has been completed. If the board is bent or distorted at the time of separation, cracks may occur in the chip capacitors. Carefully choose a separation method that minimizes the bending of the circuit board.

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CROSS REFERENCE

P/N	COMPANY	SAMSUNG	AVX	JOHANSON	KEMET	KYOCERA	MURATA	NOVACAP	PANASONIC	ROHM	TAIYO - YUDEN	TDK	VITRAMON
① COMPANY	MODEL(MLCC)	CL	-	-	C	CM	GRM	-	ECJ	MCH	MK	C	VJ
② SIZE (EIA/JIS)	0201(0603)	03	-	-	-	03	33	-	Z	-	063	0603	-
	0402(1005)	05	0402	R07	0402	05	36	0402	0	15	105	1005	0402
	0603(1608)	10	0603	R14	0603	105	39	0603	1	18	107	1608	0603
	0805(2012)	21	0805	R15	0805	21	40	0805	2	21	212	2012	0805
	1206(3216)	31	1206	R18	1206	316	42-6	1206	3	31	316	3216	1206
	1210(3225)	32	1210	S41	1210	32	42-2	1210	4	32	325	3225	1210
	1808(4520)	42	1808	R29	1808	42	-	1808	-	-	-	4520	1808
	1812(4532)	43	1812	S43	1812	43	43-2	1812	-	43	432	4532	1812
	2220(5750)	55	-	-	2220	55	44-1	2221	-	-	550	5650	-
③ TEMPERATURE CHARACTERISTIC	COG(NPO)	C	A	N	G	CG	COG/CH	N	C	A	C	COG/CH	A
	P2H(N150)	P	S	-	-	P	P2H	-	P	-	P	PH	-
	R2H(N220)	R	1	-	-	R	R2H	-	R	-	R	RH	-
	S2H(N330)	S	3	-	-	S	S2H	-	S	-	S	SH	-
	T2H(N470)	T	O	-	-	T	T2H	-	T	-	T	TH	-
	U2J(N750)	U	Z	-	-	U	U2J	-	U	UJ	U	UJ	-
	S2L	L	Y	-	-	SL	SL	-	G	SL	SL	SL	-
	X7R	B	C	W	R(X)	X7R	X7R	B	B	C	BJ	X7R(B)	Y(X)
	Z5U	E	E	Z	U	-	Z5U	Z	-	E	-	Z5U	U
Y5V	F	G	Y	V	Y5V	Y5V	Y	F	F	F	Y5V	-	
④ NOMINAL CAPACITANCE		EX) 103=10,000pF 221=220pF 225=2,200,000pF=2.2μF 1R5=1.5pF 010=1pF											
⑤ CAPACITANCE TOLERANCE		B:±0.1pF C:±0.25pF D:±0.5pF F:±1% G:±2% J:±5% K:±10% M:±20% Z:-20~+80%											
⑥ RATED VOLTAGE	6.3V	Q	6	-	9	06	6.3	-	0J	-	J	0J	-
	10 V	P	Z	100	8	10	10	-	1A	4	L	1A	-
	16 V	O	Y	160	4	16	16	160	1C	3	E	1C	J
	25 V	A	3	250	3	25	25	250	1E	2	T	1E	X
	50 V	B	5	500	5	50	50	500	1H	5	U	1H	A
	100 V	C	1	101	1	100	100	101	2A	1	-	2A	B
	200V	D	2	201	2	200	200	201	2D	-	-	-	C
	250V	E	V	-	-	250	250	251	-	-	-	2E	-
	500V	G	7	501	-	500	500	501	-	-	-	-	E
	630V	H	-	-	-	630	630	-	-	-	-	2J	-
	1000V	I	A	102	-	1000	1K	102	-	-	-	3A	G
	2000V	J	G	202	-	2000	2K	202	-	-	-	3D	-
3000V	K	H	302	-	3000	3K	302	-	-	-	3F	H	
4000V	-	J	-	-	4000	-	402	-	-	-	-	-	
⑦ TERMINATION	NICKEL BARRIER	N	T	V	C	A	(GRM)	N	-	(MCH)	-	-	X
	Ag/Pd	P	1	-	-	B	(GR)	P	-	(MC)	-	-	F
⑧ PACKAGE	BULK(VINYL)	B	9	(NONE)	-	B	PB	*	X	-	B	B	B
	PAPER TAPING	C	2, 4	T, R	-	T, L	PT	T	E, V, W	K, L	T	T	C, P
	PLASTIC TAPING	E	1, 3	E, U	-	H, N	PT	-	F, Y	P, Q	T	-	T, R
	BULK CASE	P	7	-	-	C	PC	-	C	C	-	-	G

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► SAMSUNG : CL10B104KA8NNC

CL	10	B	104	K	A	8	N	N	N	C
Series	Size	Dielectric	Capacitance	Tolerance	Voltage	Thickness	Electrode/ Termination/ Plating	Products	Special	Packaging
03 = 0201 05 = 0402 10 = 0603 21 = 0805 31 = 1206 32 = 1210 43 = 1812 55 = 2220	C = C0G P = P2H R = R2H S = S2H T = T2H U = U2H L = S2L B = X7R A = X5R F = Y5V	2 significant figures + number of zeros Use "R" for decimal point	A = ±0.05pF B = ±0.1pF C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = +80,-20%	Q = 6.3V P = 10V O = 16V A = 25V B = 50V C = 100V D = 200V E = 250V G = 500V H = 630V I = 1000V	3 = 0.30 5 = 0.50 8 = 0.80 A = 0.65 C = 0.85 H = 1.60 I = 2.00 J = 2.50 L = 3.20	A = Pd/Ag/ Sn 100% N = Ni/Cu/ Sn 100% G = Cu/Cu/ Sn 100%	A = Array (2-element) B = Array (4-element) C = High - Q L = LICC N = Normal P = Automotive W = 3 terminal chip	Various	B = Bulk P = Cassette C = Paper 7" D = Paper 13" (10,000EA) E = Embossing 7" F = Embossing 13" L = Paper 13" (15,000EA) O = Paper 10" S = Embossing 10"	

► AVX : 06033C104KAT2A

0603	3	C	104	K	A	T	2	A
Size	Voltage	Dielectric	Capacitance	Tolerance	Failure Rate	Termination	Packaging	Special
0201 0402 0603 0805 1206 1210 1812 2220 2225	4 = 4V 6 = 6.3V Z = 10V Y = 16V 3 = 25V B = 50V C = 100V D = 200V E = 250V G = 500V I = 1000V	A = C0G C = X7R D = X5R E = Z5U G = Y5V	2 significant figures + number of zeros Use "R" for decimal point	B = ±0.1pF C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = +80, -20% P = GMV,+100,-0%	A = N/A	T = Sn 100% 7 = Gold Plated 1 = Pd/Ag	2 = 7" Reel 4 = 13" Reel 7 = Cassette 9 = Bulk	A = Standard T = 0.66mm S = 0.56mm R = 0.46mm

► JOHANSON : 250R14W104KV6T

250	R14	W	104	K	V	6	T
Voltage	Size	Dielectric	Capacitance	Tolerance	Termination	Marking	Packaging
2 significant figures + number of zeros	R07 = 0402 R14 = 0603 R15 = 0805 R18 = 1206 S41 = 1210 S43 = 1812 S47 = 2220 S48 = 2225 S49 = 1825 S54 = 3640	N = C0G W = X7R X = X5R Z = Z5U Y = Y5V	2 significant figures + number of zeros Use "R" for decimal point	B = ±0.1pF C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = +80, -20% P = GMV,+100,-0%	V = Ni Barrier	4 = No Mark 6 = Marking	E = 7" Reel Plastic T = 7" Reel Paper R = 13" Reel Paper U = 13" Reel Plastic None = Bulk

► KEMET : C0603C104K3RAC

C	0603	C	104	K	3	R	A	C
Series	Size	Specification	Capacitance	Tolerance	Voltage	Dielectric	Failure Rate	Termination
0402 0603 0805 1206 1210 1812 2220 2225	C = Standard A = GR900 P = Mil-C-55681 CDR01-CDR06 N = Mil-C-55681 CDR31-CDR35 Z = Mil-C-123 E = Mil Equivalent (Group A Only)	2 significant figures + number of zeros Use "R" for decimal point	B = ±0.1pF C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = +80, -20% P = +100, 0%	9 = 6.3V 8 = 10V 4 = 16V 3 = 25V 5 = 50V 1 = 100V 2 = 200V	G = C0G R = X7R P = X5R U = Z5U X = BX(Mil) V = Y5V	A = Standard M = 1.0 (Mil) P = 0.1 (Mil) R = 0.01 (Mil) S = 0.001 (Mil)	C = Ni w/Tin Plate H = Ni w/Solder T = Silver G = Gold Plated	

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► KYOCERA : CM105X7R104K25AT

CM	105	X7R	104	K	25	A	T
Series	Size	Dielectric	Capacitance	Tolerance	Voltage	Termination	Packaging
	03 = 0201 05 = 0402 105 = 0603 21 = 0805 316 = 1206 32 = 1210 42 = 1808 43 = 1812 55 = 2220	CG X8R X7R X5R Z5U Y5V Y5U	2 significant figures + number of zeros Use "R" for decimal point	B = $\pm 0.1\text{pF}$ C = $\pm 0.25\text{pF}$ D = $\pm 0.5\text{pF}$ F = $\pm 1\%$ G = $\pm 2\%$ J = $\pm 5\%$ K = $\pm 10\%$ M = $\pm 20\%$ Z = +80, -20% P = +100, 0%	04 = 4V 06 = 6.3V 10 = 10V 16 = 16V 25 = 25V 50 = 50V 100 = 100V 250 = 250V 500 = 500V 1000 = 1000V	A = Ni Barrier	T = 7" Reel (4mm Pitch) L = 13" Reel (4mm Pitch) H = 7" Reel (2mm Pitch) N = 13" Reel (2mm Pitch) B = Bulk (Vinyl Bags) C = Bulk Cassette

► MURATA : GRM188R71E104KA01D

GRM	18	8	R7	1E	104	K	A01	D
Series	Size	Thickness	Dielectric	Voltage	Capacitance	Tolerance	Individual Specification Code	Packaging
Ni Barrier	03 = 0201 15 = 0402 18 = 0603 21 = 0805 31 = 1206 32 = 1210 42 = 1808 43 = 1812 55 = 2220	3 = 0.3mm 5 = 0.5mm 8 = 0.8mm A = 1.0mm B = 1.25mm C = 1.6mm D = 2.0mm E = 2.5mm F = 3.2mm	5C = C0G R7 = X7R R6 = X5R E4 = Z5U F5 = Y5V	0J = 6.3V 1A = 10V 1C = 16V 1E = 25V 1H = 50V 2A = 100V 2E = 250V 2H = 500V 3A = 1000V	2 significant figures + number of zeros Use "R" for decimal point	B = $\pm 0.1\text{pF}$ C = $\pm 0.25\text{pF}$ D = $\pm 0.5\text{pF}$ F = $\pm 1\%$ G = $\pm 2\%$ J = $\pm 5\%$ K = $\pm 10\%$ M = $\pm 20\%$ Z = +80,-20% P = +100, 0%		D = 7" Reel Paper L = 7" Reel Plastic J = 13" Reel Paper K = 13" Reel Plastic B = Bulk C = Bulk Cassette T = Bulk Tray

► NOVACAP : 0603B104K250N_TM

1206	B	104	K	250	N	-	T	M
Size	Dielectric	Capacitance	Tolerance	Voltage	Termination	Thickness	Packaging	Marking
0402 0603 0805 1005 1206 1210 1808 1812 2220	N = C0G B = X7R X = BX Z = Z5U Y = Y5V	2 significant figures + number of zeros Use "R" for decimal point	B = $\pm 0.1\text{pF}$ C = $\pm 0.25\text{pF}$ D = $\pm 0.5\text{pF}$ F = $\pm 1\%$ G = $\pm 2\%$ J = $\pm 5\%$ K = $\pm 10\%$ M = $\pm 20\%$ Z = +80,-20% P = +100, 0%	2 significant figures + number of zeros	P = Pd/Ag N = Ni Barrier (Sn 100%) Y = Ni Barrier (Sn/Pb)	Per Specified	T = Reel None = Bulk W = Waffle Pack	

► PANASONIC : ECJ1EB1E104K

ECJ	1	E	B	1E	104	K
Series	Size	Packaging	Dielectric	Voltage	Capacitance	Tolerance
	Z = 0201 0 = 0402 1 = 0603 2 = 0805 3 = 1206 4 = 1210	X = Bulk E = Paper 2mm V = Paper 4mm F, Y = Plastic 4mm W = Large Reels 2mm Z = Large Reels 4mm C = Bulk Cassette	C = C0G B = X7R, X5R F = Y5V	0J = 6.3V 1A = 10V 1C = 16V 1E = 25V 1H = 50V 2A = 100V 2D = 200V	2 significant figures + number of zeros Use "R" for decimal point	C = $\pm 0.25\text{pF}$ D = $\pm 0.5\text{pF}$ F = $\pm 1\%$ J = $\pm 5\%$ K = $\pm 10\%$ M = $\pm 20\%$ Z = +80, -20%

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▶ ROHM : MCH182C104KKN

MCH	18	2	C	104	K	K	N
Series	Size	Voltage e	Dielectric	Capacitance	Tolerance	Packaging	Marking/Thickness
	15 = 0402 18 = 0603 21 = 0805 31 = 1206 32 = 1210 43 = 1812	4 = 10V 3 = 16V 2 = 25V 5 = 50V	A = C0G C = X7R F = Y5V	2 significant figures + number of zeros Use "R" for decimal point	B = ±0.1pF C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = +80,-20% P = +100, 0%	K = 7" Reel Paper P = 7" Reel Plastic L = 13" Reel Paper Q = 13" Reel Plastic B = Bulk C = Bulk Cassette	N = Marked Special Thickness

▶ TAIYO-YUDEN : TMK107BJ104K_T

T	M	K	107	BJ	104	K	-	T
Voltage	Type	Termination	Size	Dielectric	Capacitance	Tolerance	Special	Packaging
A = 4V J = 6.3V L = 10V E = 16V T = 25V U = 50V	M = Multilayer V = Hi Q	K = Ni Barrier	105 = 0402 107 = 0603 212 = 0805 316 = 1206 325 = 1210 432 = 1812 550 = 2220	CG = C0G CH = C0H CJ = C0J CK = C0K BJ = X5R, X7R F = Y5V	2 significant figures + number of zeros Use "R" for decimal point	C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = +80,-20%	Various	T = Reel B = Bulk

▶ TDK : C1608X7R1E104KT

C	1608	X7R	1E	104	K	T
Series	Size	Dielectric	Voltage	Capacitance	Tolerance	Packaging
	0603 = 0201 1005 = 0402 1608 = 0603 2012 = 0805 3216 = 1206 3225 = 1210 4532 = 1812 5650 = 2220	CG X7R Z5U Y5V	0J = 6.3V 1A = 10V 1C = 16V 1E = 25V 1H = 50V	2 significant figures + number of zeros Use "R" for decimal point	C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = +80, -20%	T = Reel B = Bulk

▶ VITRAMON : VJ0603Y104KXXMC

VJ	0603	Y	104	K	X	X	M	C
Series	Size	Dielectric	Capacitance	Tolerance	Termination	Voltage	Marking	Packaging
	0402 0603 0805 1206 1210 1812 2225	X = BX A,N = C0G Y = X7R U = Z5U H = X8R	2 significant figures + number of zeros Use "R" for decimal point	B = ±0.1pF C = ±0.25pF D = ±0.5pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20% Z = +80, -20% P = +100, 0%	X = Silver, Ni Barrier Tin Plated	J = 16V X = 25V A = 50V B = 100V C = 200V	M = Marking A = No Marking	C = 7" Reel Paper T = 7" Reel Plastic P = 13" Reel Paper R = 13" Reel Plastic B = Bulk